ALLIANCE MEMORY MDS REPORT

Part Number:	**AS4C8M32MSA-6BIN**
Part Weight:	**168.725mg**

NO.	Material	Type	Component wt (mg)	Substances	Purpose	CAS No.	Element wt (%)	Weight (mg)	wt % of Total unit wt	PPM
1	Molding Compound	G1250	93.595	Epoxy Resin	Resin		5.50%	5.148	3.0510%	30,510
				Phenol resin	Resin		4.50%	4.212	2.4962%	24,962
				Silica(Fused)	filler	60676-86-0	89.70%	83.955	49.7583%	497,583
				Carbon Black	Additive	1333-86-4	0.30%	0.281	0.1664%	1,664
2	Substrate	BT	46.825	832NX-A	BT core		51.28%	24.012	14.2314%	142,314
				AUS308	Solder Mask		7.55%	3.535	2.0953%	20,953
				Cu	Trace	7440-50-8	40.54%	18.983	11.2508%	112,508
				Ni	Plating	7440-02-0	0.56%	0.262	0.1554%	1,554
				Au	Plating	7440-57-5	0.07%	0.033	0.0194%	194
3	DAF	EM700	0.577	Solid Epoxy Resin	Base material		12.50%	0.072	0.0427%	427
				Phenol Resin	Base material		12.50%	0.072	0.0427%	427
				Fused Silica	Base material	60676860	35.00%	0.202	0.1197%	1,197
				Synthrtic Rubber	Base material		40.00%	0.231	0.1368%	1,368
4	Wire	AG0B	0.668	Ag	Base material	7440-22-4	89.10%	0.595	0.3528%	3,528
				Au	Base material	7440-57-5	7.40%	0.049	0.0293%	293
				Pd	Base material	7440/5/3	3.50%	0.023	0.0139%	139
5	Solder Ball	M705	22.318	Tin (Sn)	Base material	7440-31-5	96.50%	21.537	12.7645%	127,645
				Ag	Base material	7440-22-4	3.00%	0.670	0.3968%	3,968
				Cu	Base material	7440-50-8	0.50%	0.112	0.0661%	661
6	Die	0.12mm	4.742	Si	Chip	7440-21-3	100.00%	4.742	2.8105%	28,105
								168.725	100.0000%	1,000,000